

**ABSTRACT OF THE DISCLOSURE**

The invention provides semiconductor devices that are excellent in mountability. The invention also provides manufacturing methods, circuit substrates and electronic equipments for the same. A method of manufacturing a semiconductor device includes lowering the height of at least one of a plurality of external terminals that are electrically connected to a semiconductor chip mounted on one surface of a substrate and sealed with resin, and that are provided on another surface of the substrate in plural rows and plural columns.